

IN THE CLAIMS:

1. (Canceled)

2. (Currently Amended) The infrared communication device according to claim 4 8 wherein the first lens has a semi-cylindrical shape.

3. (Currently Amended) The infrared communication device according to claim 4 8 wherein the first lens has an elongated semi-spherical shape.

4. (Canceled)

5. (Currently Amended) The infrared communication device according to claim 4 8 wherein the first lens is elongated in a horizontal direction.

6. (Currently Amended) The infrared communication device according to claim 4 8 further comprises a reflective cup enclosing the first lens.

7. (Canceled)

8. (New) An infrared communication device comprising:

a substrate having a rectangular shape in plan view comprising a longitudinal X-direction, a lateral Y-direction, and an upper surface having an electrode pattern

formed thereon;

an IC chip and other electronic parts mounted on the electrode pattern on the upper surface;

a plurality of infrared rays emitting elements mounted on the substrate and arranged in the X-direction;

an infrared rays receiving element mounted on the substrate at a position in the X-direction;

the infrared rays emitting elements and the infrared rays receiving element being connected to the IC chip and the electronic parts for operation;

a resin covering the infrared rays emitting elements, the infrared rays receiving element, the IC chip, and the electronic parts mounted on the substrate;

a first lens formed on the resin so as to be elongated in the X-direction to have opposite longitudinal ends and provided on the infrared rays emitting elements;

a semispherical second lens formed on the resin so as to be provided on the infrared rays receiving element;

a sectional shape of the first lens and a position of each of the infrared rays emitting elements with respect to the sectional shape of the first lens being selected, so that infrared rays radiation range is expanded in the X-direction over the two opposing ends of the first lens; and,

a shield member for shielding the infrared rays emitting element, the infrared rays receiving element, the IC chip, and the electronic parts.